

*12-27-01
P.M.*
196273US-0 CONT

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF : :

Ende SHAN, et al. : GROUP ART UNIT: 2823

SERIAL NO.: New Rule 1.53(b) : EXAMINER: EATON
Continuation Application

FILED: Herewith : :

FOR: LOW TEMPERATURE :
METALLIZATION PROCESS

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In advance of prosecution, please amend the above-identified application as follows:

IN THE SPECIFICATION

page 4, line 22, replace "deposited. E.g.", with --deposited; e.g.--

IN THE CLAIMS

Please amend the claims as follows:

- X Sub B1*
1. (Amended) A method of forming a layer of metal on a substrate, comprising:
 - i) depositing a seed layer of the metal on a first substrate surface, said seed layer being sufficient to cover said first substrate surface;